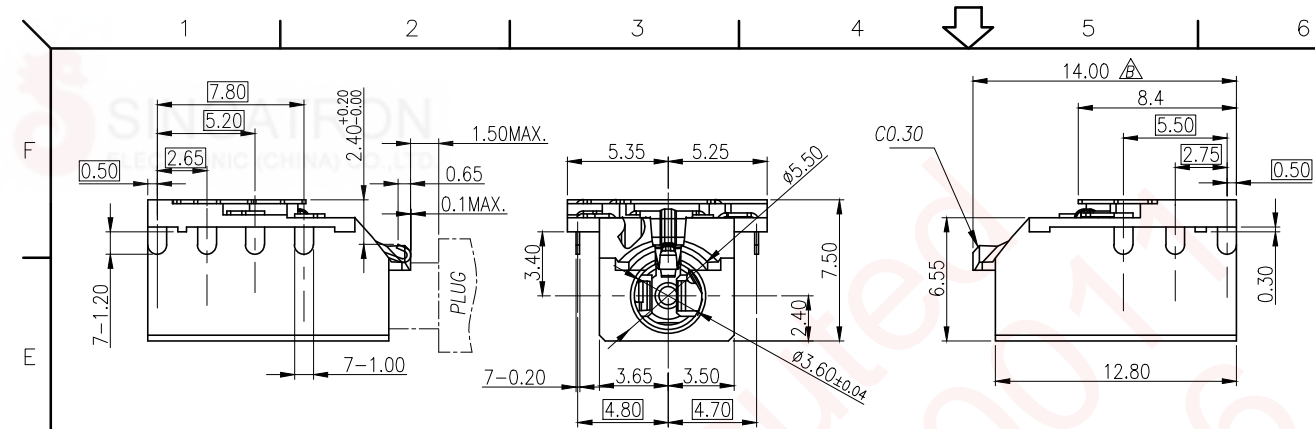
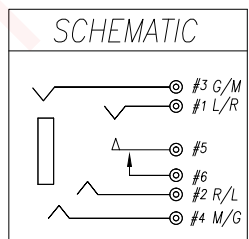
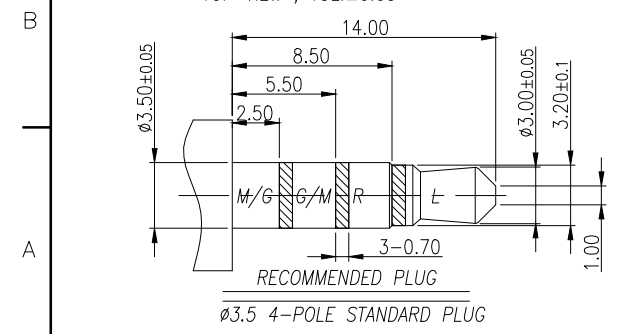
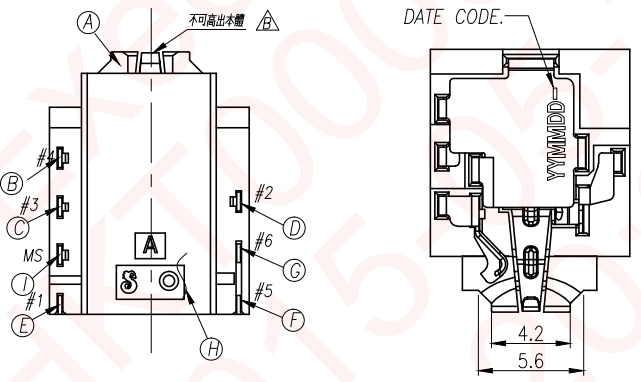
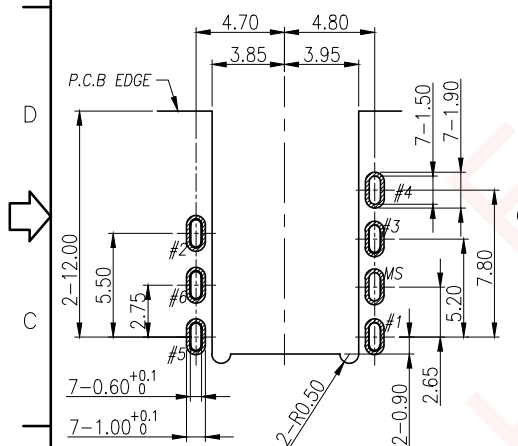


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:T141008-1A	ROBIN	2015.01.12
B	ECN NO:S150405-C	JIANG	2015.05.18



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500V DC .
 - CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
 - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
 - LIFE TEST: 5,000 CYCLES.
 - INSERTION FORCE: 0.3-3.0Kgf ,
 - WITHDRAWAL FORCE: 0.3-3.0 Kgf,
 - AFTER TEST, CONTACT RESISTANCE: 100mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:



J	DUMMY	1	STAINLESS STEEL,0.20T	Ni 60u"Min.
I	SHELL	1	COPPER ALLOY, 0.2T	Ni 60u"Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER AREA; ALL OVER 50u" Ni.
F	TRANSFER	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; Matte Sn 80u" ON SOLDER AREA; ALL OVER 50u" Ni.
E	TIP	1	COPPER ALLOY, 0.2T	
D	RING-A	1	COPPER ALLOY, 0.2T	
C	EARTH	1	COPPER ALLOY, 0.2T	
B	RING-B	1	COPPER ALLOY, 0.2T	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5Ø PHONE JACK		
DWN	JIANG	PART NO. 2SJ3095-056111F	
CHKD	CERRY	SCALE 4:1	UNIT: mm
APVD	LIAO	SIZE: A3	SHEET: 1 OF 1
REV: B			
CUSTOMER COPY			